

1 ABSTRACT OF THE DISCLOSURE

2 A semiconductor packaging structure mainly has a lead frame with a die
3 pad and a plurality of leads, a wall portion formed by molding compound
4 positioned around a periphery of the lead frame, a chip mounted on the die pad and
5 electrically connected with the plurality of lead via gold wires, and a cover
6 mounted on the wall portion to enclose the chip. An interval is defined between the
7 die pad and the plurality of leads for filling with an isolating resin, the interval
8 further communicates with multiple gaps and each gap is defined between two
9 adjacent of the plurality of leads, wherein each gap is also filled with the isolating
10 resin.